

What is claimed is:

1. A chip resistor comprising:

a substrate having opposite parallel symmetrical first and second surfaces, and a central longitudinal plane of symmetry;

separate and spaced first and second resistive layers on the first and second surfaces, respectively, electrically connected in parallel to each other; and

the first and second surfaces of the substrate being symmetrically located with respect to and equidistant from the central longitudinal plane so that when electrical current passes through the resistive layers, a temperature distribution within the substrate will be substantially symmetrical about the central longitudinal plane of the substrate for eliminating thermal bending thereof.

2. The chip resistor of claim 1 wherein the first resistive layer and the second resistive layer are thick film resistive layers.

3. The chip resistor of claim 1 wherein the first resistive layer and the second resistive layer are thin film resistive layers.

4. The chip resistor of claim 1 wherein the first resistive layer and the second resistive layer are foil resistive layers.

